



PIXIS-XO: 400B

1340 x 400 imaging array | 20 x 20 µm pixels | Direct detection

The PIXIS-XO series of fully integrated imaging cameras utilizes back-illuminated (BI) and back-illuminated, deepdepletion (BR) CCDs without AR coating, for direct detection of the widest range of X-rays between ~ 10 eV and 30 keV (AR coated devices are not useful for X-ray energies < 500eV). With a 1340 x 400 imaging array, 20 μ m pixels, 100% fill factor, low noise electronics and -90° C thermoelectric cooling with either air or water, this system is ideal for worry-free operation in research and OEM environments. The rotatable conflat flange with high-vacuum-seal design, software selectable gains and readout speeds make these cameras well suited for ultra-high vacuum applications.

FEATURES	BENEFITS	
Back-illuminated deep depletion and back-illuminated CCD, with no AR coating	Provides very low X-ray flux imaging, high sensitivity and high spatial resolution	
2 Mhz / 16-bit readout 100 kHz / 16-bit readout	High speed readout for rapid image acquisition; Slow speed readout for high sensitivity with wide dynamic range, high signal-to-noise ratio (SNR) and excellent energy resolution	
Software selectable gains for each digitization speed	Allows optimization of system performance for lowest noise to highest SNR	
1340 x 400 image area, 20 x 20 μm pixels	Spectroscopy format designed for high frame rate imaging	
Ultra low noise electronics	Best possible system performance	
Flexible user-selectable binning & readout	Total flexibility to optimize experiments and SNR	
Kinetics	Custom readout mode offers microsecond resolution	
Deep thermoelectric air cooling	Maintenance-free operation - NO need for a liquid circulator or additional power supply	
Deep thermoelectric water cooling	Vibration free operation	
Conflat vacuum interface	Industry-standard, high-vacuum compatibility	
TTL input and output	External Trigger input with programmable polarity; TTL output with exposure or readout monitor	
USB 2.0 interface	Seamless, plug-and-play connection to PC notebooks & desktops; Easy OEM integration	
Optional: LightField® (for Windows 10/8/7, 64-bit) Or WinView/Spec (for Windows 8/7/XP, 32-bit)	• • • • • • • • • • • • • • • • • • • •	
PICAM (64-bit) / PVCAM (32-bit) software development kits (SDKs)	Compatible with Windows 10/8/7 (64-bit), and Linux (contact factory for an update) Universal programming interfaces for easy custom programming.	
LabView® Scientific Imaging ToolKit (SITK™)	Predefined VIs for easy integration of camera controls into large experiment	

Applications:

X-ray Spectroscopy, EUV Lithography and X-ray Plasma Diagnostics

PIXIS-XO:400 Rev. P1



SPECIFICATIONS

	PIXIS-XO: 400B	PIXIS-XO: 400BR	
CCD Image Sensor	Princeton Instruments exclusive; scientific-grade 1; MPP; back-illuminated (BI); no AR coating (B) for sensitivity between ~10 eV to 20 keV.	Princeton Instruments exclusive; scientific-grade 1; NIMO; back-illuminated deep-depletion (BR); no AR coating for sensitivity between ~10 eV to 30 keV.	
Dark current @ -75° C (with ambient air @ +20° C)	0.001 e-/p/sec (typical) 0.005 e-/p/sec (max)	0.03 e-/p/sec (typical) 0.065 e-/p/sec (max)	
CCD format	1340 x 400 imaging pixels; 20 x 20 μm pixels; 10	00% fill factor; 13.3 x 13.3 mm (optically centered)	
Deepest cooling temperature, TE air cooling [*] (with ambient air @ +20° C)	-90° C typical; -75° C guaranteed		
Thermostating precision	±0.05° C		
Cooling method	Thermoelectric air or liquid cooling (CoolCUBE II required)		
Full well	Single pixel:100 ke- (typical), 60 ke- (minimum)High Sensitivity node:250 ke- (typical), 220 ke- (minimum)High Capacity node:1000 ke- (typical), 750 ke- (minimum)		
ADC speed/bits	100 kHz/16-bit and 2 MHz/16-bit		
System read noise @100 kHz @2 MHz	3.0 e- rms (typical), 5 e- rms (max) 11 e- rms (typical), 16 e- rms (max)		
Vertical shift speed	<15 µsec/row (programmable)		
Non-linearity	<1% @ 100 kHz <2% @ 2 MHz		
Software selectable gains	1, 2, 4 e- (high sensitivity); 4, 8, 16 e- (high capacity); available at all speeds		
Data interface	USB2.0 (5m interface cable provided); Optional Fiberoptic interface is available for remote operation		
I/O signals	Two MCX connectors for programmable frame readout, shutter, trigger in		
Operating environment	+5° C to +30° C non-condensing		
Bakeout temperature	70° C (maximum)		
Vacuum Compatibility	10 ⁻⁸ Torr		
Certification	CE		
Dimensions / Weight	16.59 cm (6.53") x 11.81 cm (4.65") x 11.38 cm (4.48") (L x W x H) / 2.27 kg (5 lbs)		

All specifications subject to change

* The minimum temperature attainable is dependent on the vacuum condition - temperature can be lowered w/lower vacuum

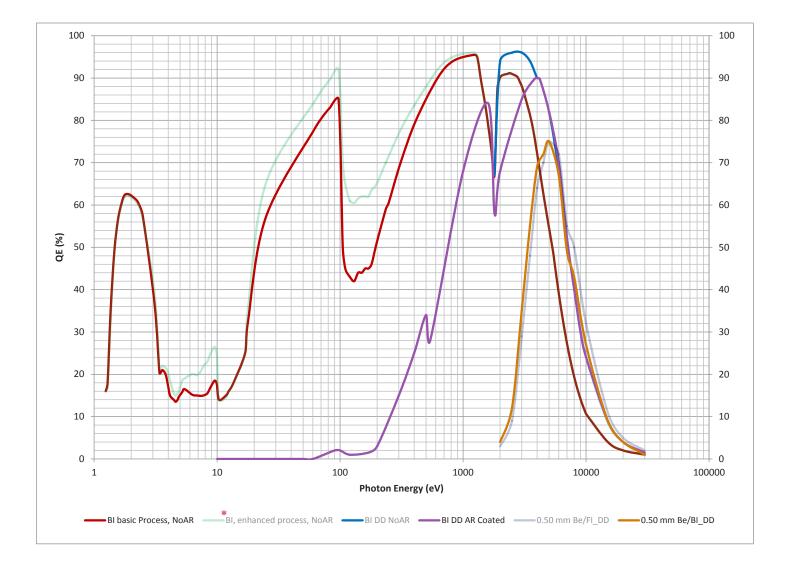
Spectral Rate

es	@100 kHz Full Vertical Binning (FVB)	60 fps
	@ 2 MHz Full Vertical Binning (FVB)	315 fps
	@ 2 MHz (0.2 mm high)	1300 fps

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Quantum Efficiency Curve



* - For reference purpose only

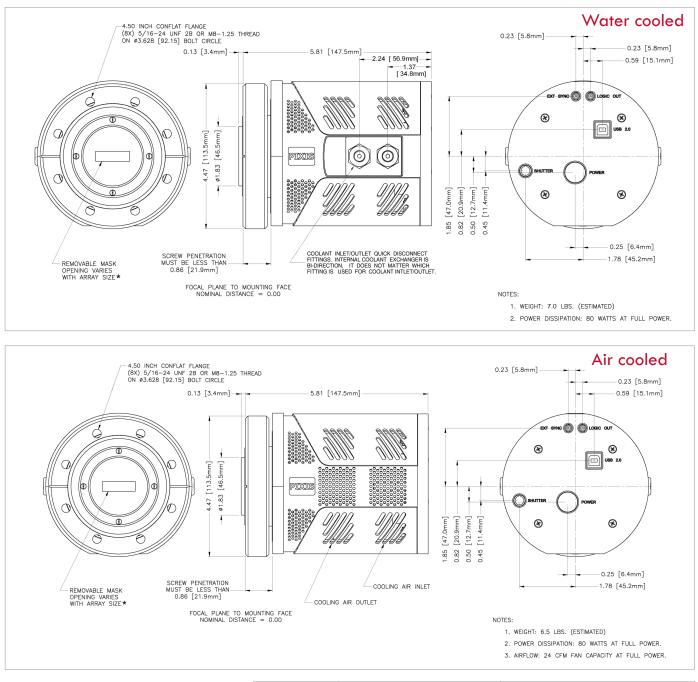
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OUTLINE DRAWING





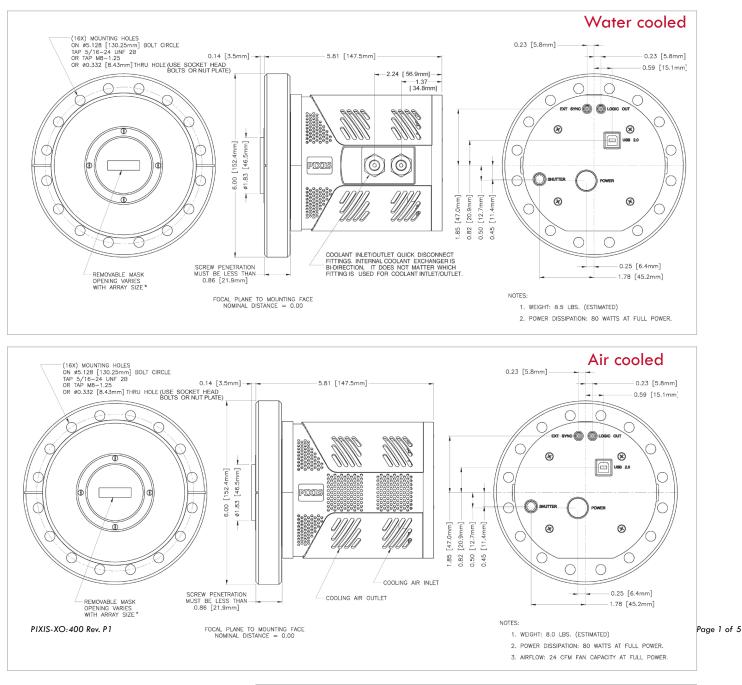
CCD Array	CCD Image Area inches (mm)	Mask Opening ± .001 inches (± .0254 mm)
1340 x 400	1.055 x 0.315 (26.8 x 8.0)	1.052 x 0.311 (26.721 x 7.899)

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